19th European Wet & 48th European CMP Users Meeting

Wet-Session: Thursday, April 10, 2025, 13:15 – 17:55

CMP-Session: Friday, April 11, 2024, 2025, 9:00 – 13:10

imec, Kapeldreef 75, B-3001 Leuven, Belgium

Organized by European CMP&WET Usergroup

Agenda Thursday, April 10th

12:30 – 13:15 Welcome Coffee, Tea, Softdrinks and Light Lunch

13:15 Opening Remarks & Welcome
Knut Gottfried
Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany

Wet Processes: Session 1

Session Chair: Knut Gottfried, Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany

13:20 Leveraging Megasonic Energy and Molecular Engineering for Low-Stress Post-CMP Cleaning Strategies
Jason Keleher
Lewis University, Romeoville, IL, USA

13:45 Integrated Metal Etch and Photoresist Strip Solution for SiC Manufacturing
Bernhard Hammerl
Siconnex GmbH, Hof bei Salzburg, Austria

14:10 Substitution of EKC265 for Post TSV Etch Cleaning Applications
Maksym Myndyk[1], Catharina Rudolph[1] and Harold Le Tulzo[2]
[1]Fraunhofer IZM-ASSID, Dresden, Germany and [2]Technic France, La Pleine St Denis, France

14:35 Method to Improve the Total Thickness Variation of Thinned Substrates Employing Integrated Metrology in Wet Chemical Processes
Martin Huber
NexGen Wafer Systems GmbH, Villach, Austria

15:00 Lift-off Processes from Different Perspectives; Use Cases
Benedikt Risse
Veeco GmbH, Aschheim, Germany

15:25 Coffee Break

Wet Processes: Session 2 and Tutorial CMP

Session Chair: Gerfried Zwicker, zwickerconsult, Berlin, Germany

16:00 Characterization of Cyanide-free Silver Electrolytes for the Production of Electrical Functional Contacts by Electrodeposition in Structured Photoresist
Seda Canli and Lothar Dietrich
Fraunhofer IZM, Berlin, Germany

16:15 Bonding pad corrosion
Ehsan Shafahian
imec, Leuven, Belgium

16:40 Effective, Safe, Recyclable: Innovation's Role in Phasing Out Toxic Products
Rogelio J. Gomez-Pineiro, Diane Bijou, Loriana Celeste, Gael Galantine, Anais Passelande, Harold Le Tulzo, Marine Audouin, and Jerome Daviot
Technic France, La Plaine St Denis, France

17:05 Tutorial: Copper CMP Application Tutorial
Federico Barbieri
Entegris/CMC Materials, Barry / Vale of Glamorgan, United Kingdom

17:55 End of Wet Users Meeting / time for networking and discussion

19:00 Workshop Dinner at Restaurant "De Hoorn"
Sluisstraat 79, 3000 Leuven

Agenda Friday, April 11th

8:30 – 9:00 Good Morning Coffee, Tea, Softdrinks

9:00 Opening Remarks
Martin Kulawski
Advaplan, Espoo, Finland

CMP Processes: Session 1

Session Chair: Martin Kulawski, Advaplan, Espoo, Finland

9:05 Effects of Conditioning Disc Designs on the Tribological, Vibrational, Thermal, Kinetic, Pad Micro-Textural and Pad Wear Characteristics of Silicon Carbide CMP Processes
Ara Philipossian[2], Uma Rames Krishna Lagudu[1], Thomas Mooney[1], Waldo Wang[1], Walter Schoenhofen[1], Yasa Sampurno[2], Leonard Borucki[2]
[1]3M Company, St. Paul, MN, USA and 3M Deutschland GmbH, Neuss, Germany; [2]Araca, Tucson, AZ, USA

9:40 Comparison of Different CMP Endpoint Techniques
Catarina Regra Da Silva
imec, Leuven, Belgium

10:05 Geometric Surface Energy
Boris Brodmann
OptoSurf GmbH, Ettlingen, Germany

10:30 Shaping Your Future CMP Processes with Bruker Tribolab CMP2.0
Mohamadou Diew
Bruker Nano Surface and Metrology Division, Palaiseau, France

10:45 Estimating the Sustainability of Chemical Mechanical Polishing with the imec.netzero Model
Karl Ceulemans
imec, Leuven, Belgium

11:00 Coffee Break

CMP Processes: Session 2

Session Chair: Catharina Rudolph, Fraunhofer IZM-ASSID, Dresden, Germany

11:30 Tribological, Thermal, Kinetic, and Surface Microtextural Characterization of Prime p-Type <100> Silicon Wafer CMP for Direct Wafer Bonding Applications
Ara Philipossian[1], Michelle Yap[1], Catherine Yap[1], Yasa Sampurno[1], Glenn Whitener[2], Jason Keleher[3], Len Borucki[1]
[1]Araca, Tucson, AZ, USA; [2]Fujimi Corp., Tualatin, OR, USA; [3]Lewis University, Romeoville, IL, USA

11:55 From Research to Production: The Latest AFM Technologies for the CMP Industry
Romain Bourrellier and Lars Vitense
Park Systems GmbH, Mannheim, Germany

12:20 Polymer CMP: Roadmap to Sustainable Alternatives
Denis Dochain
imec, Leuven, Belgium

12:45 The Effect of Megasonic Agitation (Flucto-CMP) on Removal Rates with Novel H_2O_2-based SiC Slurry
Jason Keleher
Lewis University, Romeoville, IL, USA

13:10 End of CMP Users Meeting / time for networking and discussion
Coffee, Tea, Softdrinks, Snacks and Light Lunch